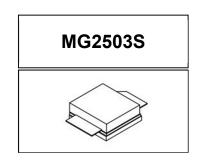
40W, 2-3GHz 28V RF LDMOS FETs

Description

The MG2503S is a 40-watt, internally matched, single ended LDMOS FETs, designed for multiple applications within full band 2.0-3.0GHz.

It can be used in Class AB/B and Class C for all typical modulation formats, for CW and pulsed, linear or saturated applications.

• Typical Performance (On Innogration 2-3GHz fixture with device soldered):



VDS=28V Idq=100mA Vgs=2.45V CW						
F(MHz)	Pin (dBm)	Psat (dBm)	Psat (W)	I(A)	Gain (dB)	Eff(%)
2000	34.4	45.53	36	2.08	11.1	61.3
2200	31.8	45.54	36	2.47	13.7	51.8
2400	33	46.30	43	3.60	13.3	42.3
2600	32.3	46.90	49	3.65	14.6	47.9
2800	34.8	47.10	51	3.50	12.3	52.3
3000	34.7	45.30	34	3.00	10.6	40.3

•Typical Performance (On Innogration 2-2.5GHz fixture with device soldered):

VDS=28V Idq=50mA Vgs=2.4V CW						
F(MHz)	Pin (dBm)	Pout (dBm)	Pout (W)	I(A)	Gain (dB)	Eff(%)
2000	31	46.00	40	2.27	15.0	62.6
2100	32.6	46.10	41	2.35	13.5	61.9
2200	31.7	46.00	40	2.49	14.3	57.1
2300	31.6	46.00	40	2.54	14.4	56.0
2400	33	46.00	40	2.55	13.0	55.8
2500	33.3	46.00	40	2.48	12.7	57.3

Features

- High Efficiency and Linear Gain Operations
- Integrated ESD Protection
- Excellent thermal stability, low HCI drift

Suitable Applications

- S band amplifier
- ISM applications
- Cellular amplifier

Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
DrainSource Voltage	V _{DSS}	+65	Vdc

- Large Positive and Negative Gate/Source Voltage Range for Improved Class C Operation
- Pb-free, RoHS-compliant

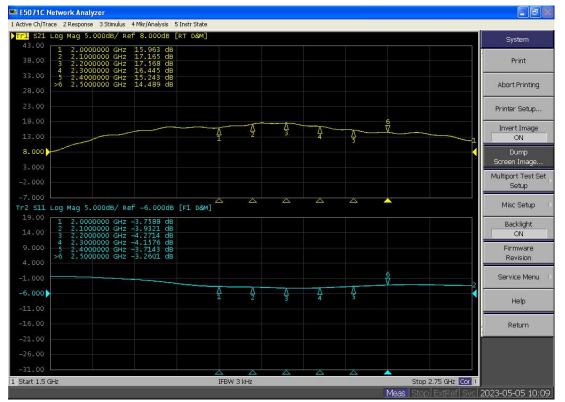
Document Number: MG2503S Product Datasheet V1.0

GateSource Voltage	V_{GS}	-10 to +10	Vdc
Operating Voltage	Vdd	+32	Vdc
Storage Temperature Range	Tstg	-65 to +150	°C
Case Operating Temperature	Tc	+150	°C
Operating Junction Temperature	TJ	+225	°C

Table 2. Thermal Characteristics

Characteristic	Symbol	Va	lue	Un	nit	
Thermal Resistance, Junction to Case	Cynisol	Value		Onic		
$T_c = 85^{\circ}C$, DC test		Rejc 1.		.3 °C/		
Table 3. ESD Protection Characteristics						
			Class			
Test Methodology			-			
Human Body Model (per JESD22A114)			Class 2			
Table 4. Electrical Characteristics (TA = 25 °C unless otherw	ise noted)	1	1	1	1	
Characteristic	Symbol	Min	Тур	Max	Unit	
DC Characteristics						
Zero Gate Voltage Drain Leakage Current	IDSS			100	μA	
$(V_{DS} = 65V, V_{GS} = 0 V)$	IDSS			100	μΛ	
Zero Gate Voltage Drain Leakage Current				1	μA	
$(V_{DS} = 28 \text{ V}, V_{GS} = 0 \text{ V})$	DSS				μΑ	
GateSource Leakage Current						
(V _{GS} = 10 V, V _{DS} = 0 V)	I _{GSS}		1		μΑ	
Gate Threshold Voltage	M. (0)		2.0		v	
$(V_{DS} = 28V, I_D = 450 \ \mu A)$	V _{GS} (th)		2.0		v	
Gate Quiescent Voltage			2.4			
$(V_{DD}$ = 28 V, I _D = 50mA, Measured in Functional Test)	$V_{GS(Q)}$		2.4		V	
Functional Tests (On Demo Test Fixture, 50 ohm system) V_{DD} = 28	8 Vdc, I _{DQ} = 50 mA,	f = 2000 -2500	MHz, Pulse 0	CW Signal	•	
Power Gain	Gp	12	13		dB	
Drain Efficiency@P3dB	η _D		55		%	
3 dB Compression Point	P-3dB	40			W	
_oad Mismatch (In Innogration Test Fixture, 50 ohm system):	/ _{DD} = 28 Vdc, I _{DQ} =	50 mA, f = 250	0 MHz		·	
VSWR 5:1 at 40W pulse CW Output Power	No Device D	egradation				

2-2.5GHz



TYPICAL CHARACTERISTICS

Figure 2. Network analyzer output S11/S21 (VDS=28V IDQ=200mA VGS=2.95V)

Figure 3. Test Circuit Component Layout

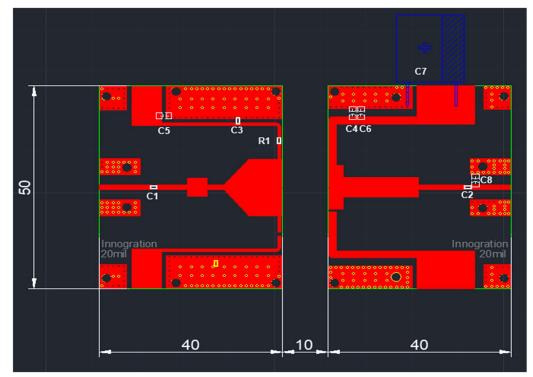


Table 5. Test Circuit Component Designations and Values

Part	description	Model	
R1	7.50Ω	Chip Resistor	
C1,C2,C3	20pF 600F		
C5,C6	10UF 1210		
C4	20pF MQ10111		
C7	470UF/63V		
C8	0.3 pF MQ10111		
РСВ	20mil Rogers4350B		

2-3GHz



TYPICAL CHARACTERISTICS

Figure 3. Network analyzer output S11/S21 (VDS=28V IDQ=200mA VGS=2.95V) Figure 3. Test Circuit Component Layout

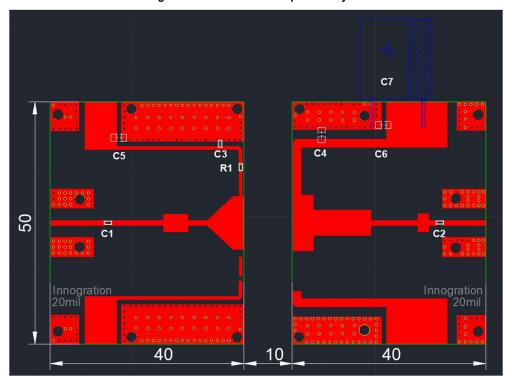
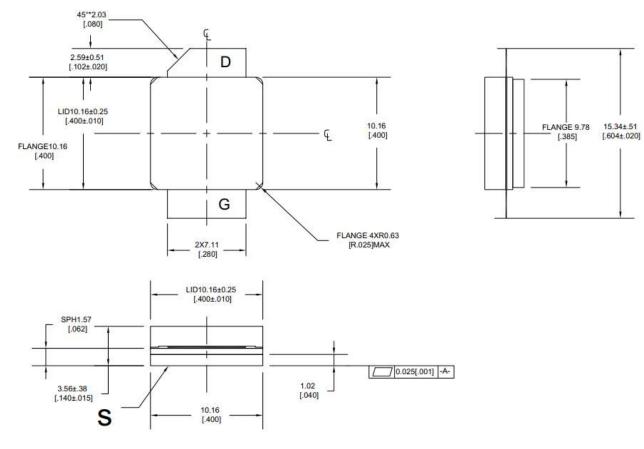


Table 6. Test Circuit Component Designations and Values

Part	description	Model	
R1	7.50Ω	Chip Resistor	
C1, C3	15pF 600F		
C5,C6	10uF 1210		
C2,C4	10pF 600F		
C7	470UF/63V		
РСВ	20mil Rogers4350B		

Package Outline

Earless flanged ceramic package; 2 leads



Unit: mm [inch]

Tolerance .xx +/- 0.01 .xxx +/- 0.005 inches

Revision history

Table 5. Document revision history

Date	Revision	Datasheet Status
2023/5/5	Rev 1.0	Product Datasheet

Application data based on SYX-23-17/18

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